TOSHIBA Photocoupler GaAlAs IRed & Photo-IC

TLP115

High Speed, Long Distance Isolated Line Receiver

Microprocessor System Interfaces

Digital Isolation For A / D, D / A Conversion

Computer-Peripheral Interfaces

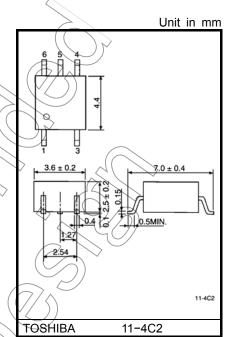
Ground Loop Elimination

The TOSHIBA mini flat coupler TLP115 is small outline coupler, suitable for surface mount assembly.

TLP115 consists of a GaAlAs light emitting diode, optically coupled to an integrated high gain, high speed shielded photo detector whose output is an open collector schottky clamped transistor.

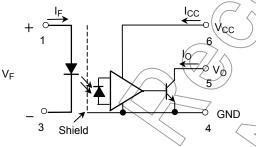
The shield, which shunts capacitively coupled common noise to ground, provides a guaranteed transient immunity specification of 1000V//µs

- Input current thresholds: IF=10mA (max.)
- Switching speed: 10MBd (typ.)
- Common mode transient immunity: ±1000V / µs (min.)
- Guaranteed performance over temp.: 0~70°C
- Isolation voltage: 2500Vrms (min.)
- UL recognized: UL1577, file no. E67349



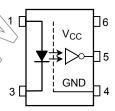
Weight: 0.09 g (typ.)

Schematic



Note. A 0.1µF bypass capacitor must be connected between pins 4 and 6.

Configuration(top view)



- 1: Anode
- 3: Cathode
- 4 : GND
- 5 : V_O(Output)
- 6: V_{CC}

Truth Table(positive logic)

Input	Output
Н	L
L	Н

Absolute Maximum Ratings (Ta = 25°C)

	Characteristic		Symbol	Rating	Unit
	Forward current		lF	20	mA
	Pulse forward current	(Note 1)	I _{FP}	40	mA
FE	Peak transient forward current	(Note 2)	I _{FPT}	1	Α
	Reverse voltage		V _R	5	V
	Output current		IO	25	mA
ţoţ	Output voltage	ige		7	V <
Detector	Supply voltage (1 minute maximum)		V _{CC}	7	\ \ \ (
	Output power dissipation		Po	40	mW
Оре	erating temperature range		T _{opr}	−40~85	(°C)
Sto	rage temperature range		T _{stg}	-55~125	-¢
Lea	d solder temperature(10s)		T _{sol}	260	7)%
	ation voltage ;, 1min., RH ≤ 60%,	Note 4)	BVS	2500	Vrms

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are within the absolute maximum ratings.

Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc.).

(Note 1) 50% duty cycle, 1ms pulse width.

(Note 2) Pulse width ≤ 1µs, 300pps./

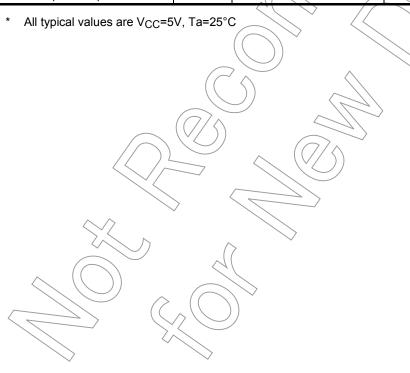
Recommended Operating Conditions

Characteristic	Symbol	Min.	Ту́р.	Max.	Unit
Input voltage, low level	V _{FL}	-3	0	1.0	V
Input current, high level	IFH	13	7 16	20	mA
Supply voltage	V _{CC}	4.5	5	5.5	V
Fan out (TTL load, each channel)	N	_	_	8	_
Operating temperature	Topr	0	_	70	°C

Note: Recommended operating conditions are given as a design guideline to obtain expected performance of the device. Additionally, each item is an independent guideline respectively. In developing designs using this product, please confirm specified characteristics shown in this document.

Electrical Characteristics (unless otherwise specified, Ta = $0\sim70^{\circ}$ C, V_{CC} = $4.5\sim5.5$ V, $V_{FL}\leq1.0$ V)

Characteristic	Symbol	Test Condition	Min. Typ.*		Max.	Unit
Forward voltage	V _F	I _F =10mA, Ta=25°C	_	1.65	1.80	V
Forward voltage temperature coefficient	V _F / Ta	I _F =10mA	_	2	_	mV / °C
Reverse current	I _R	V _R =5V, Ta=25°C	_	-((10	μΑ
Capacitance between terminals	C _T	V _F =0, f=1MHz, Ta=25°C	_	45		pF
High level output current	lau	V _F =1.0, V _O =5.5V	(\	$(\vee Z)$	250	
	Іон	V _F =1.0, V _O =5.5V, Ta=25°C	7	0.5	10	μΑ
Low level output voltage	V _{OL}	I _F =10mA I _{OL} =13mA(sinking)		0.4	0.6	٧
"H level output→ L level output" input current	lFH	I _{OL} =13mA(sinking) V _{OL} =0.6V		_	10	mA
High level supply current	Icch	V _{CC} =5.5V, I _F =0	\sim	7	15	> mA
Low level supply current	I _{CCL}	V _{CC} =5.5V, I _F =16mA)) —	⟨r2	18/) mA
Input-output insulation leakage current	Is	V _S =3540V, t=5s Ta=25°C (Note 4)	_		100	μА
Isolation resistance	R _S	R.H.≤ 60%, V _S =500V DC Ta=25°C (Note 4)	5×10 ¹⁰	1014)) –	Ω
Stray capacitance between input to output	CS	V _S =0, f=1MHz Ta=25°C (Note 4)	((0.8	_	pF



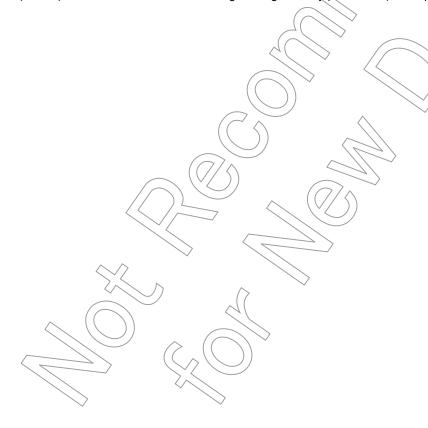
Switching Characteristics(V_{CC} = 5V, Ta = 25°C)

Characteristic	Symbol	Test Cir– cuit	Test Condition	Min.	Тур.	Max.	Unit
Propagation delay time (H→L)	t _{pHL}	1	$\begin{array}{l} \text{I}_{\text{F}}\text{=}0 \rightarrow 16\text{mA} \\ \text{C}_{\text{L}}\text{=}15\text{pF}, \text{R}_{\text{L}}\text{=}350\Omega \end{array}$	_	60	120	ns
Propagation delay time $(L \rightarrow H)$	t _{pLH}	1	$\begin{array}{l} I_F = 16 \rightarrow 0 mA \\ C_L = 15 pF, \ R_L = 350 \Omega \end{array}$		60	120	ns
Output rise fall time (10–90%)	t _r , t _f	2	$R_L=350\Omega$, $C_L=15pF$ $I_F=0 \rightleftharpoons 16mA$		30	-	ns
Common mode transient immunity at high output level	СМН	2	I _F =0mA, V _{CM} =400V _{p-p} V _{O(min)} =2V, R _L =350Ω	1000		-	V / µs
Common mode transient immunity at low output level	CML	2	I_{F} =16mA, V_{CM} =400 V_{p-p} $V_{O(max)}$ =0.8 V , R_{L} =350 Ω	1000	-	1	V / µs

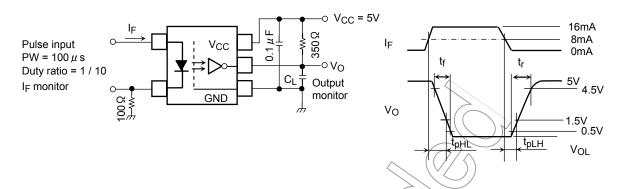
(Note 4) Device considered a two-terminal device: Pins 1 and 3 shorted together, and pins 4, 5 and 6 shorted together.

(Note 5) The V_{CC} supply voltage to each TLP115 isolator must be bypassed by 0.1µF capacitor. This can be either a ceramic or solid tantalum capacitor with good high frequency characteristic and should be connected as close as possible to package V_{CC} and GND pins of each device.



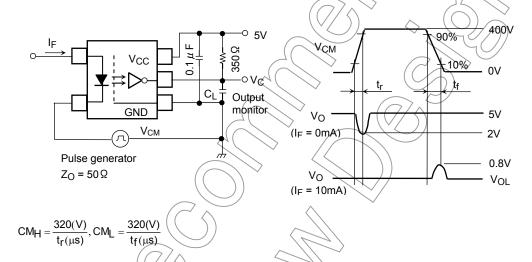


Test Circuit 1: Switching Time Test Circuit



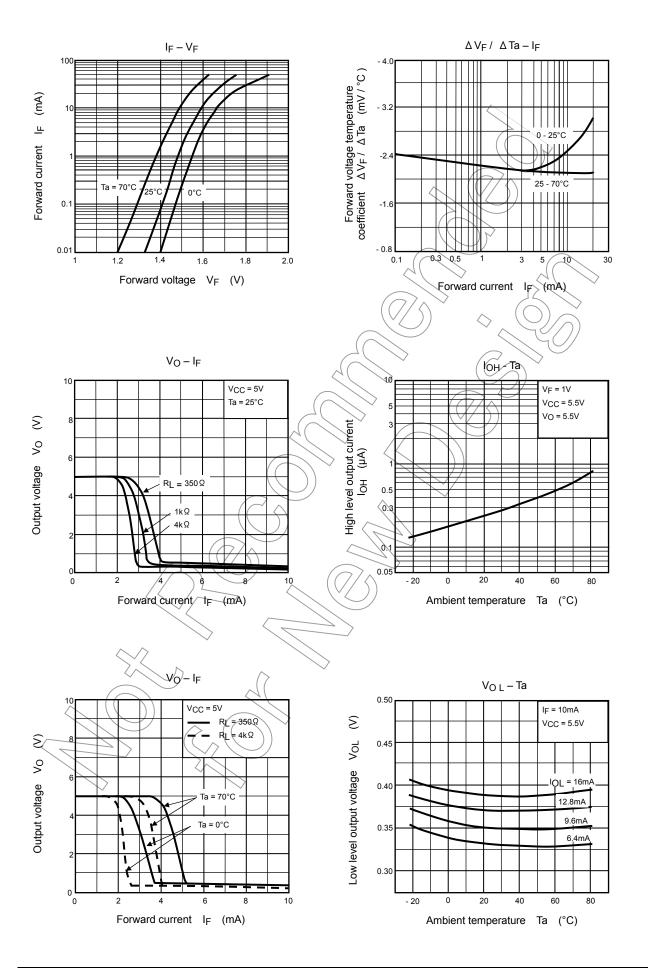
CL is approximately 15pF which includes probe and stray wiring capacitance.

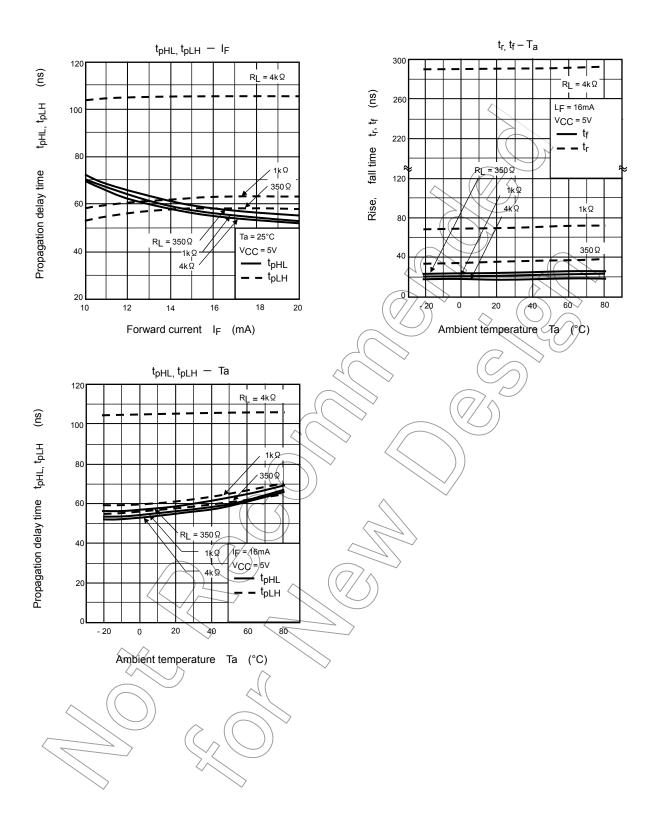
Test Circuit 2: Common Mode Transient Immunity Test Circuit



C_L is approximately 15pF which includes probe and stray wiring capacitance.







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